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SHIMIZU et al.(10) **Pub. No.: US 2024/0237203 A1**(43) **Pub. Date: Jul. 11, 2024**(54) **WIRING SUBSTRATE**(71) Applicant: **IBIDEN CO., LTD.**, Ogaki (JP)(72) Inventors: **Keisuke SHIMIZU**, Ogaki (JP); **Fumio NISHIWAKI**, Ogaki (JP); **Ryoya KIMURA**, Ogaki (JP)(73) Assignee: **IBIDEN CO., LTD.**, Ogaki (JP)(21) Appl. No.: **18/408,617**(22) Filed: **Jan. 10, 2024**(30) **Foreign Application Priority Data**

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(57)

ABSTRACT

A wiring substrate includes a first wiring part including a first insulating layer and a first conductor layer laminated on the first insulating layer, and a second wiring part formed on the first part and including a second insulating layer and a second conductor layer laminated on the second insulating layer. The thickness of the second insulating layer is smaller than that of the first insulating layer. The thickness of the second conductor layer is smaller than that of the first conductor layer. The first conductor layer has a surface on the opposite side with respect to the first insulating layer such that the arithmetic mean roughness of the surface is smaller than that of a surface of the second conductor layer on the opposite side with respect to the second insulating layer. The second part is positioned closer to the outermost surface of the substrate than the first part.

